

DB3X313F

Silicon epitaxial planar type

For small current rectification

■ Features

- Low forward voltage V_F and small reverse current I_R
- Low terminal capacitance C_t
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Basic Part Number

Dual DB2J313 (Series)

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	Single	200	mA
	Series	130	
Peak forward current	Single	300	mA
	Series	220	
Non-repetitive peak reverse surge voltage *	Single	1.0	A
	Series	0.7	
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

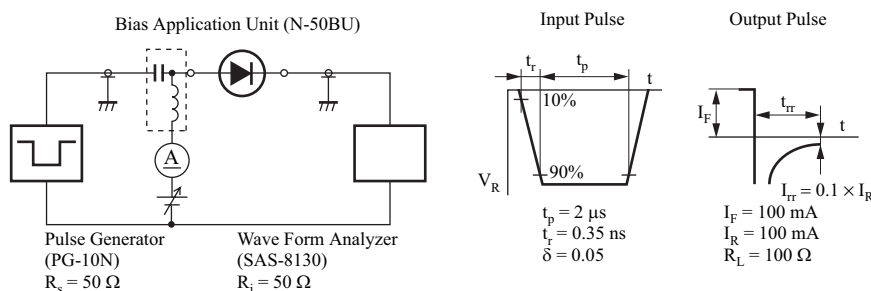
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			50	μA
Terminal capacitance	C_t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		3.8		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100 \text{ mA}, I_{Tr} = 0.1 \times I_R, R_L = 100 \Omega$		1.5		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 1 GHz

*: t_{rr} measurement circuit

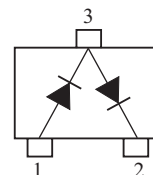


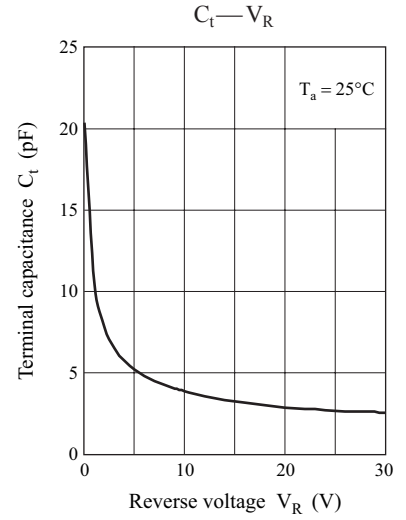
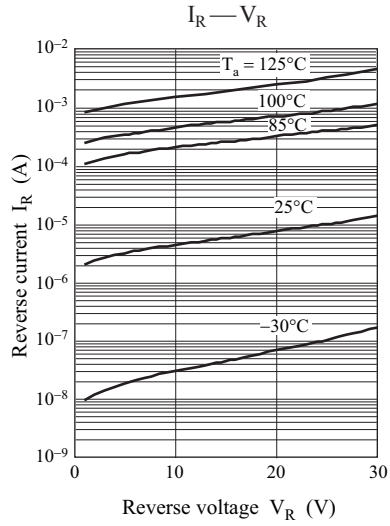
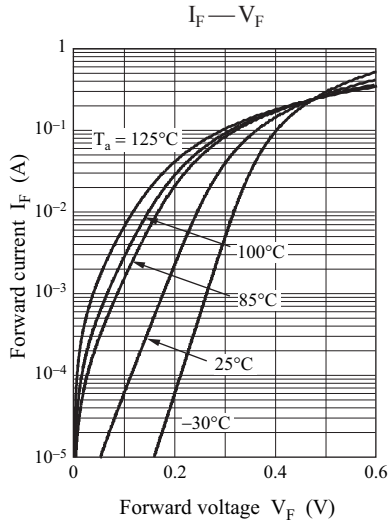
■ Package

- Code
Mini3-G3-B
- Pin Name
1: Anode-1 3: Cathode-1
2: Cathode-2 Anode-2

■ Marking Symbol: 4Q

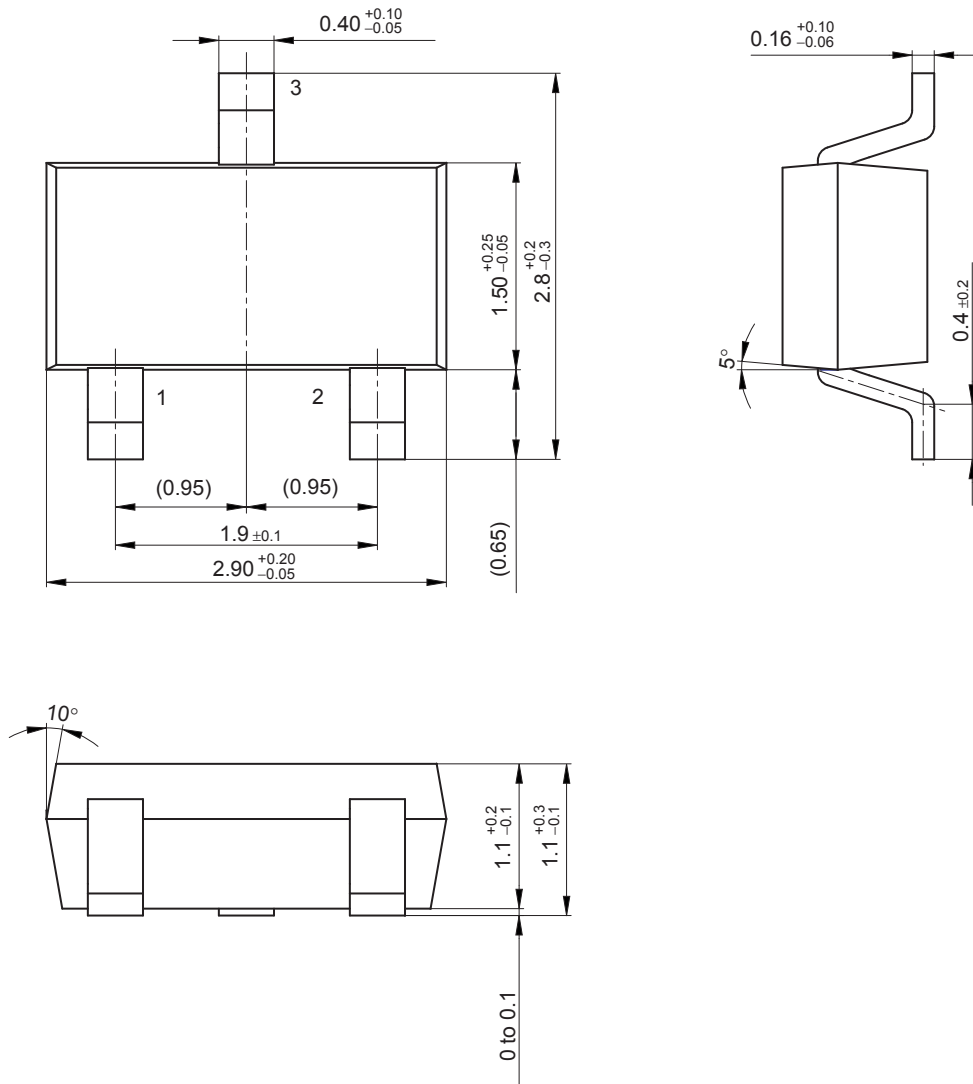
■ Internal Connection





Mini3-G3-B

Unit: mm



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